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 TI Sintered composite as thermal expansion buffer
 PA Hitachi Cable, Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 4 pp.
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PI	JP 57152438	A	19820920	JP 1981-37538	19810316
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AB For use as a thermal expansion buffer in soldering a Si wafer
 and Cu lead wires, powdered Fe-Ni alloys containing 36-42%
 Ni are coated with Mo or W 0.2 μ thick, mixed with 20-80% powdered
 Cu having an elec. conductivity $\geq 100\%$, compacted, sintered at 700°
 for 30 min, and rolled repeatedly with intermediate annealing 10 min at
 700°. The thermal expansion coefficient and elec. conductivity increases
 linearly with increasing Cu content. Without the coating, the values
 remain unchanged.